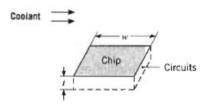
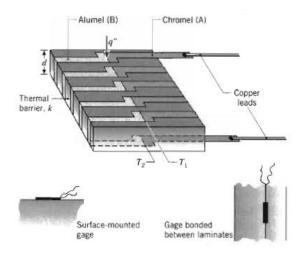
## Heat Transfer Problem Sheet-1: Generalized problems of conduction, convection and radiation (from Incropera, DeWitt, Bergman, Lavine 6<sup>th</sup> Ed)

- The heat flux through a wood slab 50 mm thick, whose inner and outer surface temperatures are 40 and 20°C, respectively, has been determined to be 40 W/m². What is the thermal conductivity of the wood?
- A freezer compartment consists of a cubical cavity that is 2 m on a side. Assume the bottom to be perfectly insulated. What is the minimum thickness of styrofoam insulation (k = 0.030 W/m \* K) that must be applied to the top and side walls to ensure a heat load of less than 500 W, when the inner and outer surfaces are -10 and 35°C?
- A square silicon chip (k = 150 W/m·K) is of width w = 5 mm on a side and of thickness t = 1 mm. The chip is mounted in a substrate such that its side and back surfaces are insulated, while the front surface is exposed to a coolant.



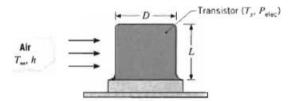
If 4 W are being dissipated in circuits mounted to the back surface of the chip, what is the steady-state temperature difference between back and front surfaces?

- A gage for measuring heat flux to a surface or through a laminated material employs five thin-film, chromel/ alumel (type K) thermocouples deposited on the upper and lower surfaces of a wafer with a thermal conductivity of 1.4 W/m · K and a thickness of 0.25 mm.
  - (a) Determine the heat flux q" through the gage when the voltage output at the copper leads is 350 μV. The Seebeck coefficient of the type-K thermocouple materials is approximately 40 μV/°C.
  - (b) What precaution should you take in using a gage of this nature to measure heat flow through the laminated structure shown?



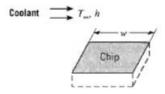
- You've experienced convection cooling if you've ever extended your hand out the window of a moving vehicle or into a flowing water stream. With the surface of your hand at a temperature of 30°C, determine the convection heat flux for (a) a vehicle speed of 35 km/h in air at -5°C with a convection coefficient of 40 W/m<sup>2</sup>· K and (b) a velocity of 0.2 m/s in a water stream at 10°C with a convection coefficient of 900 W/m<sup>2</sup>· K. Which condition would *feel* colder? Contrast these results with a heat loss of approximately 30 W/m<sup>2</sup> under normal room conditions.
- A cartridge electrical heater is shaped as a cylinder of length L = 200 mm and outer diameter D = 20 mm. Under normal operating conditions the heater dissipates 2 kW while submerged in a water flow that is at 20°C and provides a convection heat transfer coefficient of  $h = 5000 \text{ W/m}^2 \cdot \text{K}$ . Neglecting heat transfer from the ends of the heater, determine its surface temperature  $T_s$ . If the water flow is inadvertently terminated while the heater continues to operate, the heater surface is exposed to air that is also at 20°C but for which  $h = 50 \text{ W/m}^2 \cdot \text{K}$ . What is the corresponding surface temperature? What are the consequences of such an event?
- A common procedure for measuring the velocity of an air stream involves insertion of an electrically heated wire (called a hot-wire anemometer) into the air flow, with the axis of the wire oriented perpendicular to the flow direction. The electrical energy dissipated in the wire is assumed to be transferred to the air by forced convection. Hence, for a prescribed electrical power, the temperature of the wire depends on the convection coefficient, which, in turn, depends on the velocity of the air. Consider a wire of length L = 20 mm and diameter D = 0.5 mm, for which a calibration of the form,  $V = 6.25 \times 10^{-5} h^2$ , has been determined. The velocity V and the convection coefficient h have units of m/s and W/m2 · K, respectively. In an application involving air at a temperature of  $T_{\infty}$  = 25°C, the surface temperature of the anemometer is maintained at  $T_s = 75^{\circ}$ C with a voltage drop of 5 V and an electric current of 0.1 A. What is the velocity of the air?
- The free convection heat transfer coefficient on a thin hot vertical plate suspended in still air can be determined from observations of the change in plate temperature with time as it cools. Assuming the plate is isothermal and radiation exchange with its surroundings is negligible, evaluate the convection coefficient at the instant of time when the plate temperature is 225°C and the change in plate temperature with time (dT/dt) is -0.022 K/s. The ambient air temperature is 25°C and the plate measures 0.3 × 0.3 m with a mass of 3.75 kg and a specific heat of 2770 J/kg · K.

9 The case of a power transistor, which is of length L = 10 mm and diameter D = 12 mm, is cooled by an air stream of temperature T<sub>∞</sub> = 25°C.



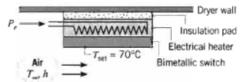
Under conditions for which the air maintains an average convection coefficient of  $h = 100 \text{ W/m}^2 \cdot \text{K}$  on the surface of the case, what is the maximum allowable power dissipation if the surface temperature is not to exceed 85°C?

A square isothermal chip is of width w = 5 mm on a side and is mounted in a substrate such that its side and back surfaces are well insulated, while the front surface is exposed to the flow of a coolant at T<sub>x</sub> = 15°C. From reliability considerations, the chip temperature must not exceed T = 85°C.



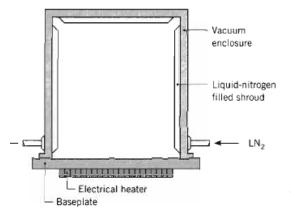
If the coolant is air and the corresponding convection coefficient is  $h = 200 \text{ W/m}^2 \cdot \text{K}$ , what is the maximum allowable chip power? If the coolant is a dielectric liquid for which  $h = 3000 \text{ W/m}^2 \cdot \text{K}$ , what is the maximum allowable power?

The temperature controller for a clothes dryer consists of a bimetallic switch mounted on an electrical heater attached to a wall-mounted insulation pad.



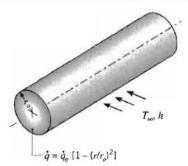
The switch is set to open at 70°C, the maximum dryer air temperature. In order to operate the dryer at a lower air temperature, sufficient power is supplied to the heater such that the switch reaches 70°C ( $T_{set}$ ) when the air temperature T is less than  $T_{set}$ . If the convection heat transfer coefficient between the air and the exposed switch surface of 30 mm² is 25 W/m² · K, how much heater power  $P_e$  is required when the desired dryer air temperature is  $T_{\infty} = 50$ °C?

A vacuum system, as used in sputtering electrically conducting thin films on microcircuits, is comprised of a baseplate maintained by an electrical heater at 300 K and a shroud within the enclosure maintained at 77 K by a liquid-nitrogen coolant loop. The circular baseplate, insulated on the lower side, is 0.3 m in diameter and has an emissivity of 0.25.



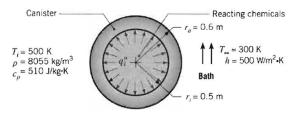
- (a) How much electrical power must be provided to the baseplate heater?
- (b) At what rate must liquid nitrogen be supplied to the shroud if its heat of vaporization is 125 kJ/kg?
- (c) To reduce the liquid-nitrogen consumption, it is proposed to bond a thin sheet of aluminum foil (ε = 0.09) to the baseplate. Will this have the desfred effect?
- Three electric resistance heaters of length L=250 mm and diameter D=25 mm are submerged in a 10 gallon tank of water, which is initially at 295 K. The water may be assumed to have a density and specific heat of  $\rho=990 \text{ kg/m}^3$  and  $c=4180 \text{ J/kg} \cdot \text{K}$ .
  - (a) If the heaters are activated, each dissipating  $q_1 = 500 \text{ W}$ , estimate the time required to bring the water to a temperature of 335 K.
  - (b) If the natural convection coefficient is given by an expression of the form  $h = 370(T_s T)^{1/3}$ , where  $T_s$  and T are temperatures of the heater surface and water, respectively, what is the temperature of each heater shortly after activation and just before deactivation? Units of h and  $(T_s T)$  are  $W/m^2 \cdot K$  and K, respectively.
  - (c) If the heaters are inadvertently activated when the tank is empty, the natural convection coefficient associated with heat transfer to the ambient air at  $T_{\infty} = 300$  K may be approximated as h = 0.70  $(T_s T_{\infty})^{1/3}$ . If the temperature of the tank walls is also 300 K and the emissivity of the heater surface is  $\varepsilon = 0.85$ , what is the surface temperature of each heater under steady-state conditions?

Radioactive wastes are packed in a long, thin-walled cylindrical container. The wastes generate thermal energy nonuniformly according to the relation  $\dot{q} = \dot{q}_o [1 - (r/r_o)^2]$ , where  $\dot{q}$  is the local rate of energy generation per unit volume,  $\dot{q}_o$  is a constant, and  $r_o$  is the radius of the container. Steady-state conditions are maintained by submerging the container in a liquid that is at  $T_{\infty}$  and provides a uniform convection coefficient h.



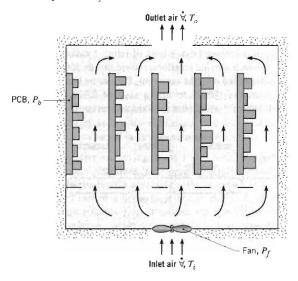
Obtain an expression for the total rate at which energy is generated in a unit length of the container. Use this result to obtain an expression for the temperature  $T_s$  of the container wall.

A spherical, stainless steel (AISI 302) canister is used to store reacting chemicals that provide for a uniform heat flux  $q_i''$  to its inner surface. The canister is suddenly submerged in a liquid bath of temperature  $T_{\infty} < T_i$ , where  $T_i$  is the initial temperature of the canister wall.



- (a) Assuming negligible temperature gradients in the canister wall and a constant heat flux  $q_i''$ , develop an equation that governs the variation of the wall temperature with time during the transient process. What is the initial rate of change of the wall temperature if  $q_i'' = 10^5 \text{ W/m}^2$ ?
- (b) What is the steady-state temperature of the wall?
- A freezer compartment is covered with a 2-mm-thick layer of frost at the time it malfunctions. If the compartment is in ambient air at 20°C and a coefficient of h = 2 W/m² · K characterizes heat transfer by natural convection from the exposed surface of the layer, estimate the time required to completely melt the frost. The frost may be assumed to have a mass density of 700 kg/m³ and a latent heat of fusion of 334 kJ/kg.

A computer consists of an array of five printed circuit boards (PCBs), each dissipating  $P_b = 20$  W of power. Cooling of the electronic components on a board is provided by the forced flow of air, equally distributed in passages formed by adjoining boards, and the convection coefficient associated with heat transfer from the components to the air is approximately  $h = 200 \text{ W/m}^2 \cdot \text{K}$ . Air enters the computer console at a temperature of  $T_i = 20^{\circ}\text{C}$ , and flow is driven by a fan whose power consumption is  $P_f = 25$  W.



- (a) If the temperature rise of the air flow,  $(T_o T_i)$ , is not to exceed 15°C, what is the minimum allowable volumetric flow rate  $\dot{\nabla}$  of the air? The density and specific heat of the air may be approximated as  $\rho = 1.161$  kg/m<sup>3</sup> and  $c_p = 1007$  J/kg · K, respectively.
- (b) The component that is most susceptible to thermal failure dissipates 1 W/cm² of surface area. To minimize the potential for thermal failure, where should the component be installed on a PCB? What is its surface temperature at this location?
- During its manufacture, plate glass at  $600^{\circ}$ C is cooled by passing air over its surface such that the convection heat transfer coefficient is  $h = 5 \text{ W/m}^2 \cdot \text{K}$ . To prevent cracking, it is known that the temperature gradient must not exceed 15°C/mm at any point in the glass during the cooling process. If the thermal conductivity of the glass is  $1.4 \text{ W/m} \cdot \text{K}$  and its surface emissivity is 0.8, what is the lowest temperature of the air that can initially be used for the cooling? Assume that the temperature of the air equals that of the surroundings.